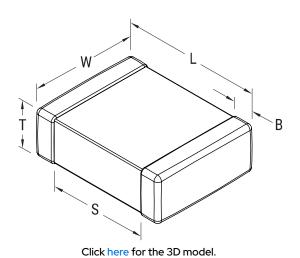


C0402C152F4GACTU

Aliases (C0402C152F4GAC7867) SMD Comm COG, Ceramic, 1,500 pF, 1%, 16 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 0402, 0.3 mm



General Information		
Series	SMD Comm COG	
Style	SMD Chip	
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I	
Features	Ultra-Stable, Low Loss, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	1.06 mg	
Shelf Life	78 Weeks	
MSL	1	

1,500 pF

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
S	0.3mm MIN
В	0.3mm +/-0.1mm

W 0.5mm +/-0.05mm Tolerance 1% T 0.5mm +/-0.05mm Voltage DC 16 VDC S 0.3mm MIN Dielectric Withstanding Voltage 40 VDC B 0.3mm +/-0.1mm Temperature Range -55/+125°C Temp. Coefficient COG Packaging Specifications Packaging T&R, 180mm, Paper Tape Packaging Quantity 10000 Dissipation Factor 0.1%1 kHz 1.0Vrms				
S 0.3mm MIN Dielectric Withstanding Voltage 40 VDC B 0.3mm +/-0.1mm Temperature Range -55/+125°C Temp. Coefficient COG Packaging Specifications Packaging T&R, 180mm, Paper Tape Packaging Quantity 10000	W	0.5mm +/-0.05mm	Tolerance	1%
B 0.3mm +/-0.1mm Temperature Range -55/+125°C Temp. Coefficient COG Packaging Specifications Packaging T&R, 180mm, Paper Tape Packaging Quantity 10000	Т	0.5mm +/-0.05mm	Voltage DC	16 VDC
Temp. Coefficient COG Packaging Specifications Packaging T&R, 180mm, Paper Tape Packaging Quantity 10000 Temp. Coefficient Cog Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) Temp. Coefficient COG 30 ppm/C, 1kHz 1.0Vrms Reference to +25°C and 0 VDC Applied (TCC)	S	0.3mm MIN	Dielectric Withstanding Voltage	40 VDC
Packaging Specifications Packaging T&R, 180mm, Paper Tape Packaging Quantity 10000 Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) 30 ppm/C, 1kHz 1.0Vrms Reference to +25°C and 0 VDC Applied (TCC)	В	0.3mm +/-0.1mm	Temperature Range	-55/+125°C
Packaging Quantity 10000 Capacitatice Charge with 30 pphyc, iknz i.ovinis Reference to +25°C and 0 VDC Applied (TCC)			Temp. Coefficient	COG
Packaging Ouantity 10000 Applied (TCC)	Packaging Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
Packaging Quantity 10000 Dissipation Factor 0.1%1 kHz 1.0Vrms	Packaging	T&R, 180mm, Paper Tape		
	Packaging Quantity 10000		Dissipation Factor	0.1% 1 kHz 1.0Vrms

n +/-0.05mm	Measurement Condition	1 kHz 1.0Vrms
mm +/-0.05mm	Tolerance	1%
mm +/-0.05mm	Voltage DC	16 VDC
mm MIN	Dielectric Withstanding Voltage	40 VDC
mm +/-0.1mm	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
, 180mm, Paper Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
00	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour
	Insulation Resistance	100 GOhms

Specifications

Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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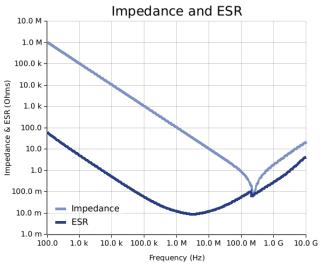


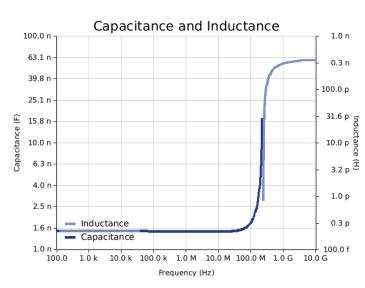
C0402C152F4GACTU

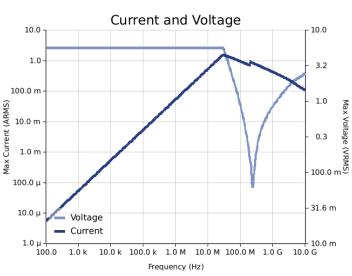
Aliases (CO402C152F4GAC7867) SMD Comm COG, Ceramic, 1,500 pF, 1%, 16 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 0402, 0.3 mm

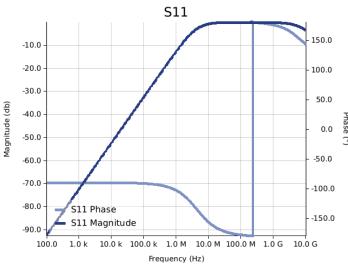
Simulations

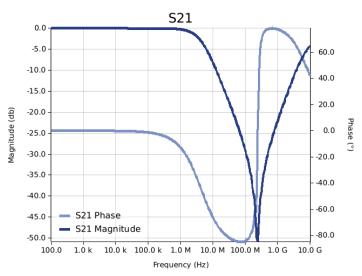
For the complete simulation environment please visit K-SIM.











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C0402C152F4GACTU

Aliases (C0402C152F4GAC7867) SMD Comm COG, Ceramic, 1,500 pF, 1%, 16 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 0402, 0.3 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is unleast at an interact temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.

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